2026 9th International Workshop on Low Temperature Bonding for 3D Integration

2026 9th International Workshop on Low Temperature Bonding for 3D Integration (LTB-3D 2026, Satellite in Kanazawa)

Date: May. 13 - 15, 2026 Venue: Kanazawa Bunka Hall, Kanazawa, Japan

Website https://imsi.jp/ltb3d/ltb3d-2026/ **Submission deadline Jan 16, 2026**

Sponsored by General Incorporated Non-profit Association - Institute for Advanced Micro-System Integration (IMSI), Japan. Co-sponsored by IEEE/EPS.

2026 9th International Workshop on Low Temperature Bonding for 3D Integration (LTB-3D 2026 Satellite in Kanazawa) will be held in May 13-15, 2026, in Kanazawa-city, Japan.

The LTB-3D is a premier conference series sponsored by General Incorporated Non-profit Association - Institute for Advanced Micro-System Integration (IMSI), and in collaboration with ECS Symposium on Semiconductor Wafer Bonding and WaferBond conferences held in Europe.

Preceding LTB-3D workshop was held in Tokyo in its 1st (2007), 2nd (2010), 3rd (2012), 4th (2014), and 5th (2017) versions, in Kanazawa in 6th (2019) version, and online in 7th (2021) version. Its 8th version (2024) was held in Nara-city. LTB-3D 2026 is again given in Kanazawa as its satellite workshop.

This workshop is focusing on the promotion of advanced research areas related to low-temperature bonding technologies, including surface activated bonding (SAB) and atomic diffusion bonding (ADB), which realize novel device structure by heterogeneous material and device integration and lead to entirely new manufacturing approaches to 3D and module integration of semiconductor devices, photonics systems, and power electronic systems. These bonding technologies have been already used for the volume production and have potential applications in wide range of manufacturing industries.

LTB-3D 2024, which will be held as a single-track face-to-face seminar to provide comprehensive information on the latest technologies and applications, as well as business opportunities, will be sponsored by IMSI, Japan, cosponsored by IEEE EPS Japan

● Presentation style

The workshop will be given in real-time, single-track session with oral and poster formats. All presenters of contributed papers are requested to attend on site.

● Scope

- Roles of Low-temperature Bonding in 3D and Hetero-Integration
- Surface Activated Bonding (SAB) and its Extensions
- Hybrid Bonding and Related Technologies
- Hydrophilic and Plasma-assisted Bonding
- Metal Bonding for High-density Interconnect
- New process for Low-temperature Bonding
- Power, RF, Photonic, and MEMS Device Applications
- New Applications of Low-temperature Bonding
- Fundamentals and Characterization
- Equipment and Quality Assessments

● Organizing Committee

Tadatomo Suga	General Chair, Meisei Univ.
Hideki Takagi	Organizing Committee Chair, AIST
Takashi Matsumae	Technical Program Chair, AIST
Naoteru Shigekawa	Osaka Metropolitan Univ.
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Natsuko Kawamata	Secretary, IMSI

● Contact point

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